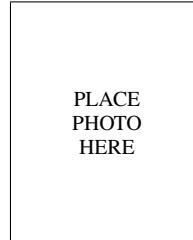


Bare Demo of IEEEtran.cls for IEEE Journals

Giuliano Sisto, *Student Member, IEEE*, and Dragomir Milojevic, *Member, IEEE*

Abstract—We present an IR-drop analysis of hybrid bonded 3D-ICs with backside power delivery network (BS-PDN) and buried power rail. A commercial power analysis tool is extended to support μ/n TSVs structures (respectively: 0.5, 0.09 μm diameter and 1, 10 Ω resistance) used to deliver power from the backside to the system. The proposed tool flow is used to evaluate IR-drop of L1 cache memory implemented on the top of a core. A 80% reduction in average static IR-drop is achieved with the BS-PDN compared to the conventional frontside. Further, 82% and 43% average and peak IR-drop reductions are obtained with n TSV compared to μ TSV.

Index Terms—IEEE, IEEEtran, journal, L^AT_EX, paper, template.



Michael Shell Biography text here.

I. INTRODUCTION

THIS demo file is intended to serve as a “starter file” for IEEE journal papers produced under L^AT_EX using IEEEtran.cls version 1.8b and later. I wish you the best of success.

mds

August 26, 2015

A. Subsection Heading Here

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John Doe Biography text here.

II. CONCLUSION

The conclusion goes here.

APPENDIX A

PROOF OF THE FIRST ZONKLAR EQUATION

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APPENDIX B

Appendix two text goes here.

Jane Doe Biography text here.

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